TITLE: ELECTRONIC ASSEMBLIES WITH FILLED NO-FLOW UNDERFILL (as amended)

INVENTORS NAME: Carlos A. Gonzalez et al.

SERIAL NO.: 10/003238

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REPLACEMENT SHEET

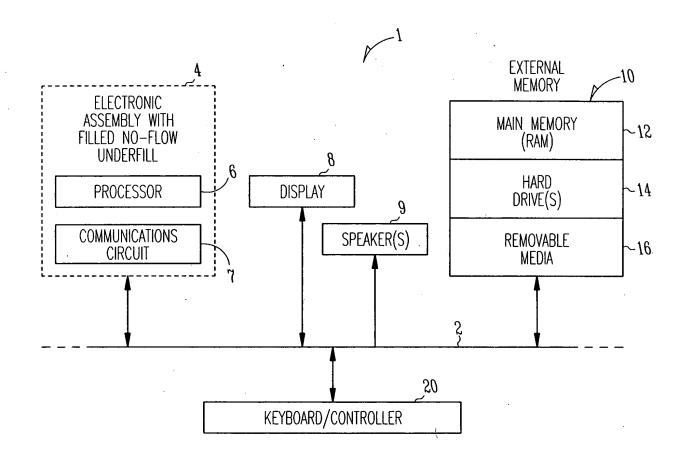


Fig. 1

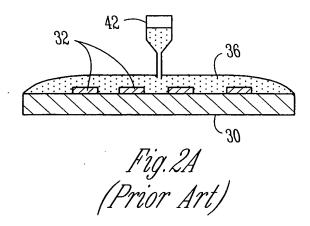
## ELECTRONIC ASSEMBLIES WITH FILLED NO-FLOW UNDERFILL (as amended) TITLE:

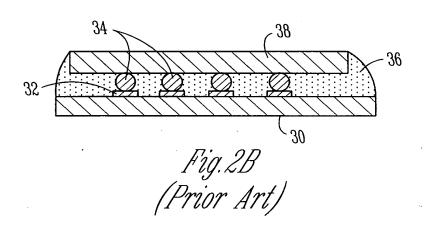
INVENTORS NAME: Carlos A. Gonzalez et al.

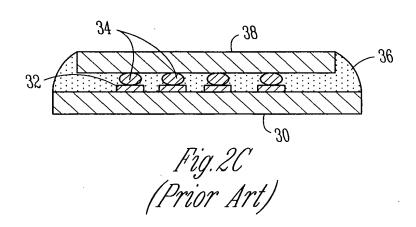
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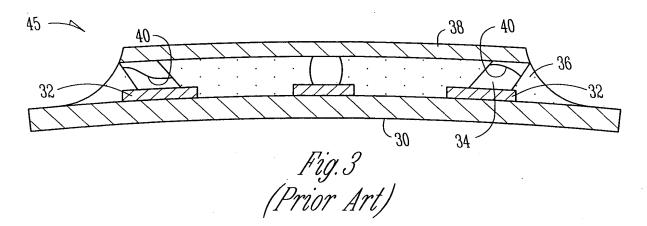
INVENTORS NAME: Carlos A. Gonzalez et al.

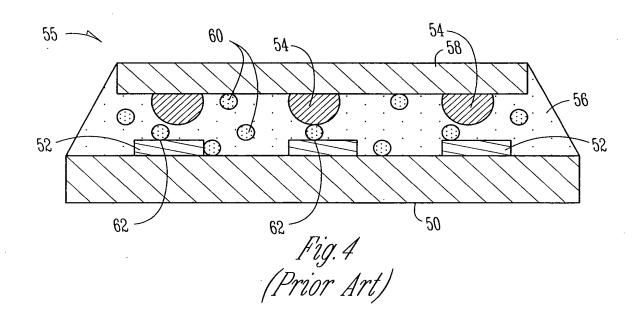
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REPLACEMENT SHEET

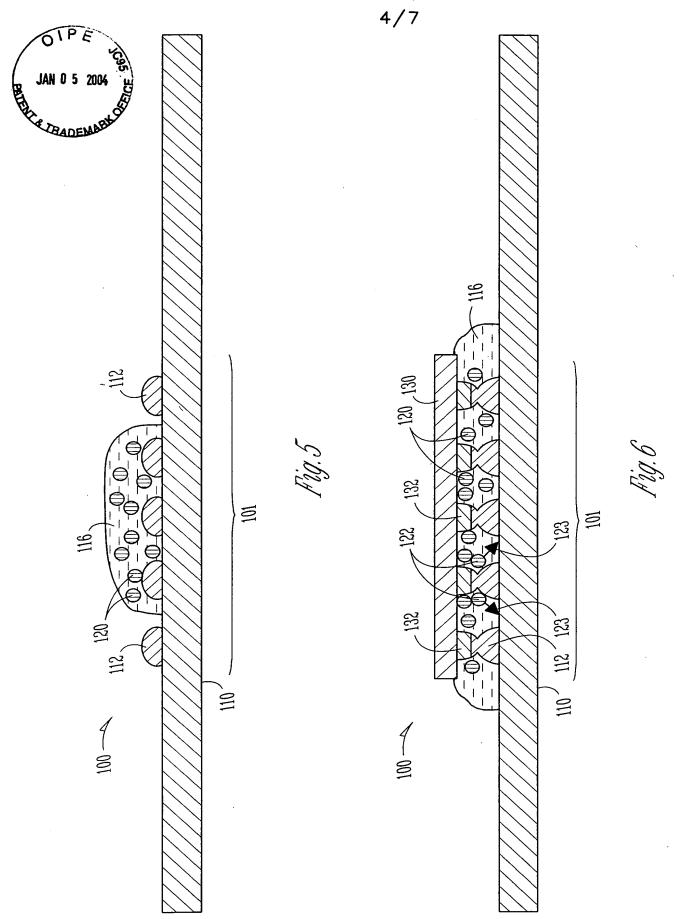






INVENTORS NAME: Carlos A. Gonzalez et al.

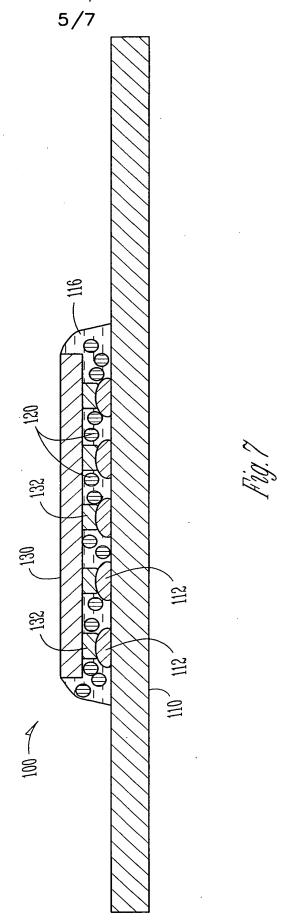
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REPLACEMENT SHEET



500 **BEGIN** 501 FABRICATE OR PROCURE A COMPONENT HAVING A PLURALITY OF TERMINALS (OPTIONAL) PRE-COAT THE TERMINALS WITH SOLDER 503 FABRICATE OR PROCURE A SUBSTRATE HAVING A COMPONENT MOUNTING AREA, THE COMPONENT MOUNTING AREA HAVING A PLURALITY OF PADS (OPTIONAL) PRE-COAT THE PADS WITH SOLDER 205 DEPOSIT A NO-FLOW UNDERFILL MATERIAL IN THE COMPONENT MOUNTING AREA OF THE SUBSTRATE - THE UNDERFILL MATERIAL IS DEPOSITED OVER THE PADS - THE UNDERFILL CAN INCLUDE A RESIN, A HARDENING AGENT, A CURING ACCELERATOR. AN AGENT TO REDUCE CTE. A FLUXING AGENT, A VISCOSITY CONTROLLING AGENT, AND/OR A FILLER 501 PLACE THE COMPONENT ON THE COMPONENT MOUNTING AREA, SUCH THAT THE COMPONENT TERMINALS ARE ALIGNED WITH CORRESPONDING PADS AND ARE SUBSTANTIALLY ENVELOPED IN THE UNDERFILL MATERIAL 509 APPLY SUITABLE PRESSURE TO CAUSE THE TERMINALS TO PHYSICALLY CONTACT THE PADS

Fig. 8A

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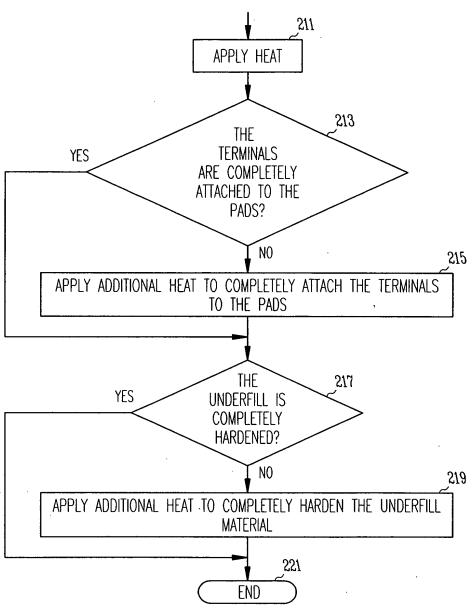


Fig.8B